

Enhancement Mode P-Channel Power MOSFET

 $TO-252/PMOS/-40V/\pm20V/-1.5V/-15A/30m\Omega$

Rev1.0





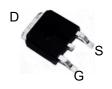
-40V, 30mΩ, -15A, Single P-Channel

1.Features

- Super Low Gate Charge
- ◆ Green Device Available
- ◆ Excellent Cdv/dt effect decline
- ◆ Advanced high cell density Trench technology
- ◆ 100% RG Tested
- ◆ 100% UIS Tested

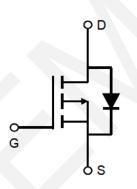
2.Applications

- Primary Side Switch
- ◆ Load Switch



TO-252 Pin Description





Schematic Diagram

3.Package Marking and Ordering Information

Part no.	Marking	Package PCS/Reel		PCS/CTN.	
WX029P04KD	029P04	TO-252	2,500	25,000	

4.Absolute Max Ratings at Ta=25°C (Note1)

Parameter	Symbol	Maximum	Units	
Drain to Source Voltage	V _{DSS}	-40	V	
Gate to Source Voltage	V_{GSS}	±20	V	
Drain Current (DC)	I _D	-15	А	
Drain Current (Pulse), PW≤300μs	I _{DP}	-60	А	
Total Dissipation	P _D	37	W	
Avalanche Energy, Single Pulsed	E _{AS}	56.25	mJ	
Junction Temperature	T _j	150	°C	
Storage Temperature	T _{stg}	-55 to +150	°C	

Note 1: Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.



5. Thermal Resistance Ratings (Note 2)

Parameter	Symbol	Value	Unit
Junction to case	$R_{ heta JC}$	3.4	°C/W
Junction to ambient	$R_{ hetaJA}$	34	°C/W

Note 2: When mounted on 1 inch square copper board t ≤ 10sec The value in any given application depends on the user's specific board design.

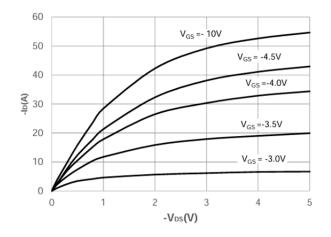
6.Electrical Characteristics at Ta=25°C (Note 3)

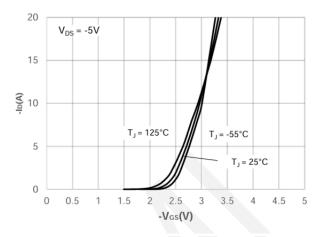
Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Units
Drain to Source Breakdown Voltage	V _{(BR)DSS}	$I_D = -250 \mu A, V_{GS} = 0 V$	-40	1	1	V
Zero-Gate Voltage Drain Current	I _{DSS}	V _{DS} = -40V, V _{GS} = 0V	ı	1	-1	μA
Gate to Source Leakage Current	I _{GSS}	$V_{GS} = \pm 20V, V_{SS} = 0V$	'	-	±100	nA
Gate Threshold Voltage	$V_{GS(th)}$	V _{DS} =V _{GS} , I _{DS} =-250μA	-1.2	-1.5	-2.3	V
Static Drain to Source On-State	R _{DS(on)}	I _D = -15A, V _{GS} = -10V	-	30	39	mΩ
Resistance	25(6)	I _D = -10A, V _{GS} = -4.5V	-	36	50	mΩ
Input Capacitance	C _{iss}	V _{GS} =0V,	-	1244	-	pF
Output Capacitance	C _{oss}	V _{DS} =-20V,	-	97	-	pF
Reverse Transfer Capacitance	C _{rss}	Frequency=1.0MHz		80	-	pF
Turn-ON Delay Time	t _{d(on)}		-	5	-	ns
Rise Time	t _r	$V_{DD} = -20V, R_{GEN} = 3\Omega$ $V_{GS} = -10V, I_{D} = -15A$	-	2	-	ns
Turn-OFF Delay Time	$t_{d(off)}$		-	51	-	ns
Fall Time	t _f		-	29	-	ns
	Q_g	V _{DS} = -20V,	-	23	-	nC
Total Gate Charge	Q _{gs}	$V_{GS} = 0 \text{ to -10V},$	-	4	-	nC
	Q_{gd}	I _D = -15A	-	4	-	nC
Diode Forward Voltage	V _{FSD}	I _S =-15A, V _{GS} = 0	-	-	-1.2	V

Note 3: Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

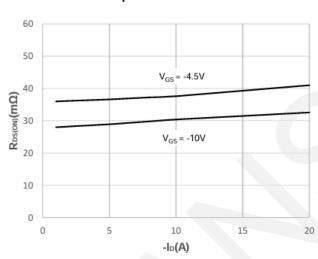


7. Typical electrical and thermal characteristics

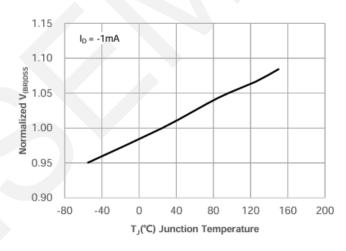




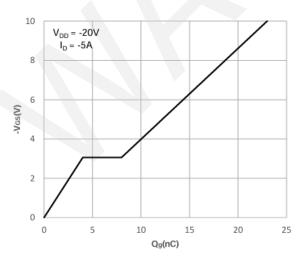
Output Characteristics



Transfer Characteristics

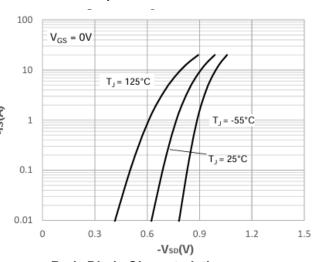


On-resistance vs. Drain Current



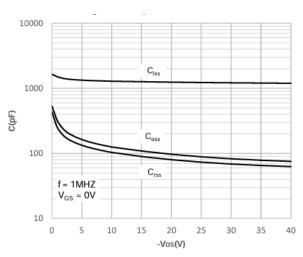
Gate Charge

Normalized Breakdown Voltage-Junction Temperature

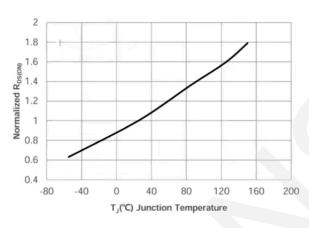


Body Diode Characteristics

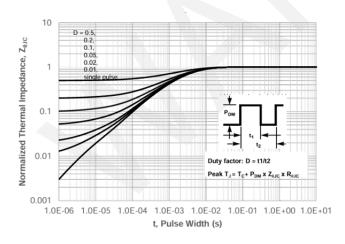




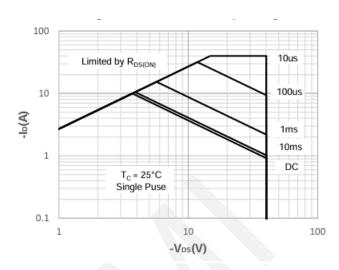
Capacitance - Vds



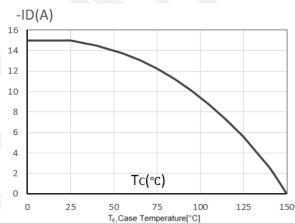
Normalized on Resistance - Junction Temperature



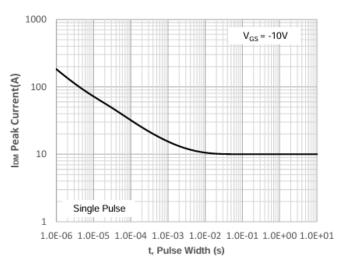
Maximum Effective Transient Thermal Impedance , Junction-to-Case



Safe Operation Area



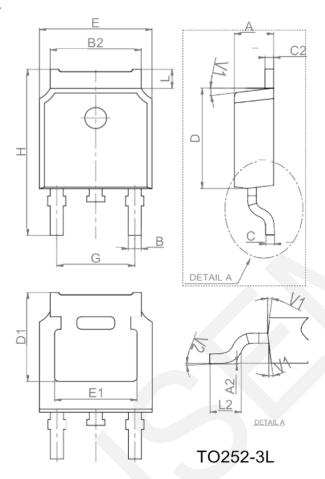
Maximum Continuous Drain Current - Case Temperature



Peak Current Capacity



8.Package Dimensions



	Dimensions						
Ref.	Millimeters			Inches			
	Min.	Тур.	Max.	Min.	Тур.	Max.	
Α	2.10		2.50	0.083		0.098	
A2	0		0.10	0		0.004	
В	0.66		0.86	0.026		0.034	
B2	5.18		5.48	0.202		0.216	
С	0.40		0.60	0.016		0.024	
C2	0.44		0.58	0.017		0.023	
D	5.90		6.30	0.232		0.248	
D1	5.30REF			0.209REF			
E	6.40		6.80	0.252	0.268		
E1	4.63			0.182			
G	4.47		4.67	0.176		0.184	
Н	9.50		10.70	0.374		0.421	
L	1.09		1.21	0.043		0.048	
L2	1.35		1.65	0.053		0.065	
V1		7°			7°		
V2	0°		6°	0°		6°	



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